What is claimed is:

1. An amorphous siliceous powder comprising Si and Al in a combined content thereof in the powder is 99.5% by mass or more in terms of their oxides; a content of Al in a first portion of the powder, having a particle size range of 15 μm or more to less than 70 μm, is 100 to 30000 ppm in terms of its oxide; a content of Al in a second portion of the powder, having a particle size range of 3 μm or more to less than 15 μm, is 100 to 7000 ppm in terms of its oxide; and a content of Al in the powder including the entire particle size range is 100 to 25000 ppm in terms of its oxide.

2. The powder according to claim 1, wherein a ratio (A/B) of (A) the content of Al in the first portion of the powder to (B) the content of Al in the second portion of the powder, is 1.0 to 20.

3. The powder according to claim 1 or 2, having a multimodal particle size distribution with at least two peaks in a frequency particle size distribution, wherein a maximum frequency value of a first peak is located between a particle size range of 15 to 70 μm, a maximum frequency value of a second peak is located between a particle size range of 3 to 10 μm and an average particle diameter is 5 to 50 μm.

4. A method for producing the amorphous siliceous powder

according to any one of claims 1 to 3, the method comprising spraying from separate burners a first raw material siliceous powder having an average particle diameter of 15 to 70 μm and a content of Al of a first Al source material of 100 to 30000 ppm in terms of its oxide, and a second raw material siliceous powder having an average particle diameter of 3 to 10 μm and a content of Al of a second Al source material of 100 to 7000 ppm in terms of its oxide, into a high temperature flame formed from a flammable gas and a supporting gas.

5. A resin composition comprising the amorphous siliceous powder according to any one of claims 1 to 3, and a resin.

6. The composition according to claim 5, wherein the resin comprises an epoxy resin.

7. A semiconductor sealing material comprising the resin composition according to claim 5 or 6.

What is claimed is:

1. An amorphous siliceous powder comprising Si and Al in a combined content thereof in the powder is 99.5% by mass or more in terms of their oxides; a content of Al in a first portion of the powder, having a particle size range of 15 μm or more to less than 70 μm, is 100 to 30000 ppm in terms of its oxide; a content of Al in a second portion of the powder, having a particle size range of 3 μm or more to less than 15 μm, is 100 to 7000 ppm in terms of its oxide; and a content of Al in the powder including the entire particle size range is 100 to 25000 ppm in terms of its oxide, wherein a ratio (A/B) of (A) the content of Al in the first portion of the powder to (B) the content of Al in the second portion of the powder, is 1.0 to 20.

2. The powder according to claim 1, having a multimodal particle size distribution with at least two peaks in a frequency particle size distribution, wherein a maximum frequency value of a first peak is located between a particle size range of 15 to 70 μm, a maximum frequency value of a second peak is located between a particle size range of 3 to 10 μm and an average particle diameter is 5 to 50 μm.

3. A method for producing the amorphous siliceous powder according to claim 1 or 2, the method comprising spraying from separate burners a first raw material siliceous powder having

an average particle diameter of 15 to 70 μm and a content of Al of a first Al source material of 100 to 30000 ppm in terms of its oxide, and a second raw material siliceous powder having an average particle diameter of 3 to 10 μm and a content of Al of a second Al source material of 100 to 7000 ppm in terms of its oxide, into a high temperature flame formed from a flammable gas and a supporting gas.

4. A resin composition comprising the amorphous siliceous powder according to claim 1 or 2, and a resin.

5. The composition according to claim 4, wherein the resin comprises an epoxy resin.

6. A semiconductor sealing material comprising the resin composition according to claim 4 or 5.